

**IN THE U.S. PATENT AND TRADEMARK OFFICE**

In re application of

Takashi SUEYOSHI et al.

Conf. 1846

Application No. 10/594,221

Group 1796

Filed September 25, 2006

Examiner O. Ojurongbe

SILICON-CONTAINING CURING COMPOSITION AND HEAT CURED  
PRODUCT THEREOF

**AMENDMENT**

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

December 14, 2009

Sir:

In response to the Official Action mailed September 14,  
2009, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing  
of claims which begins on page 2 of this paper.

**Remarks** begin on page 6 of this paper.